



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPD90P03P4L-04	<b>Issued</b>	30. April 2021
<b>MA#</b>	MA001916140		
<b>Package</b>	PG-TO252-3-11	<b>Weight*</b>	373.06 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	1.08	1.08	10799	10799
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		577	
	non noble metal	copper	7440-50-8	215.017	57.63	57.71	576364	577114
wire	non noble metal	aluminium	7429-90-5	5.910	1.58	1.58	15842	15842
encapsulation	inorganic material	zinc oxide	1314-13-2	1.216	0.33		3258	
	miscellaneous	miscellaneous	-	6.078	1.63		16292	
	plastics	epoxy resin	-	18.234	4.89		48877	
	inorganic material	silicon dioxide	60676-86-0	96.032	25.74	32.59	257419	325846
lead finish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10025	10025
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	243	244
solder	non noble metal	tin	7440-31-5	0.065	0.02		173	
	noble metal	silver	7440-22-4	0.081	0.02		216	
	non noble metal	lead	7439-92-1	3.085	0.83	0.87	8269	8658
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.14	5.15	51406	51472
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com